

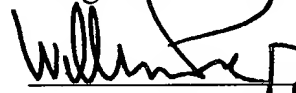
**REMARKS**

Claims 1-5 and 8-12 have been amended to eliminate reference numerals therefrom in order to place them in better form to define the features of the invention more properly and improve the examination process. The amendments to the claims are not made in view of any prior art, do not narrow the scope of the claims and thus should not give rise to any estoppel.

Should the Examiner have any questions or comments about the above, he is respectfully requested to contact the undersigned at the below-listed telephone number.

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**MARKED-UP COPY OF THE CLAIMS**

1. (Amended) A three dimensional conical horn antenna coupled image detector comprising:

a plurality of supports [30a, 30b] for supporting a horn antenna structure [20] on the upper section of a substrate [10];

a horn antenna waveguide [25] formed at the center of said horn antenna structure [20];

an image detector [40] at the lower section of said horn antenna wave guide [25];

an absorption layer [50] in said image detector [40] which has an identical width to that of said horn antenna waveguide [25]; and

a thermal isolation leg [60] in said image detector [40] which has a larger width to that of said horn antenna wave guide [25].

2. (Amended) The image detector as claimed in claim 1, wherein said thermal isolation leg [60] is manufactured in a circular shape in order to be capable of increasing the length of the leg.

5. (Twice Amended) The method as claimed in claim 3, wherein the pattern size of said sacrificial layer is identical to the external diameter of the thermal isolation leg [60] of the image detector [40].

6. (Amended) The method as claimed in claim 3, wherein the pattern size of said vanadium oxide layer is identical to the diameter of the absorption layer [50] of the image detector [40].

7. (Amended) The method as claimed in claim 3, wherein only the region around said conductive layer corresponding to the absorption layer [50] of the image detector [40] is removed by etching.

8. (Amended) The method as claimed in claim 4, wherein the pattern size of said sacrificial layer is identical to the external diameter of the thermal isolation leg [60] of the image detector [40].